



# THE DATASHEET OF SF2315E-1



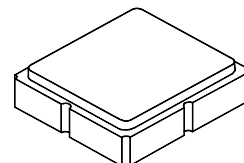
- Low-loss 782 MHz SAW Filter
- Designed for 50 ohm Source/Load
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

#### Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+25	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

**SF2315E-1**

**782 MHz  
SAW Filter**



**SM3030-8**

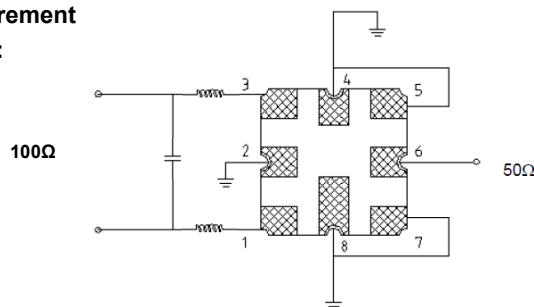
#### Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_c$			782		MHz
Insertion Loss, 777 to 787 MHz	IL			2.6	3.4	dB
Bandwidth			10	29		MHz
Amplitude Ripple, 777 to 787 MHz				0.3	1.00	dB <sub>P-P</sub>
Attenuation, Referenced to 0 dB:						dB
300 to 700 MHz			28	46		
728 to 757 MHz			10	40		
880 to 1050 MHz			28	42		
Source Impedance	$Z_S$			100		$\Omega$
Load Impedance	$Z_L$			50		$\Omega$
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A82, YWWS					
Standard Reel Quantity	Reel Size 7 inch					500 Pieces/Reel
	Reel Size 13 inch					3000 Pieces/Reel

#### Electrical Connections

Connection	Terminals
Input	1,3
Output	6
Case Ground	All others

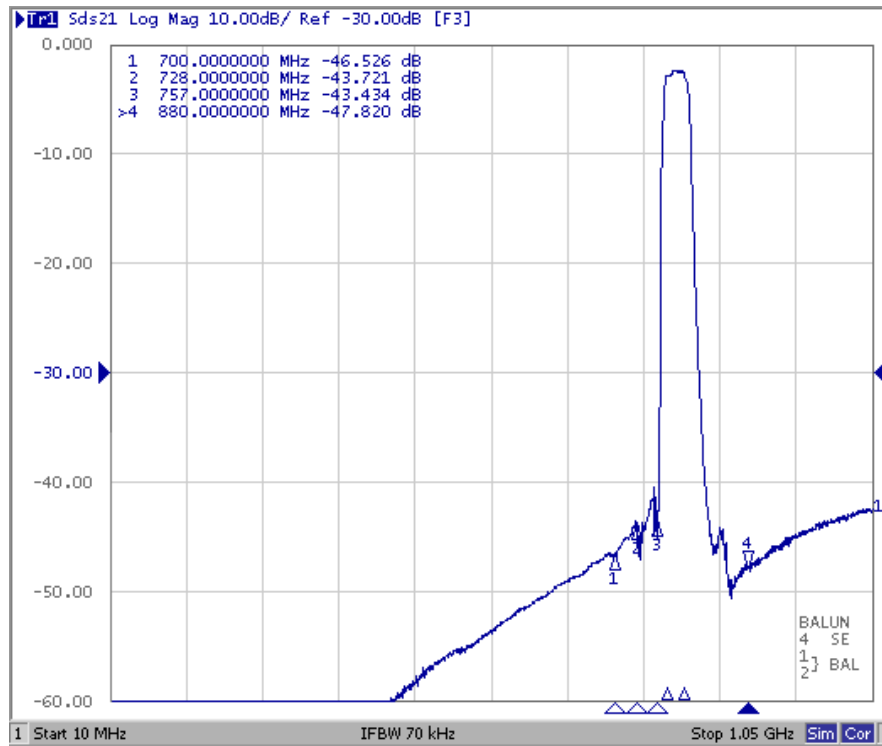
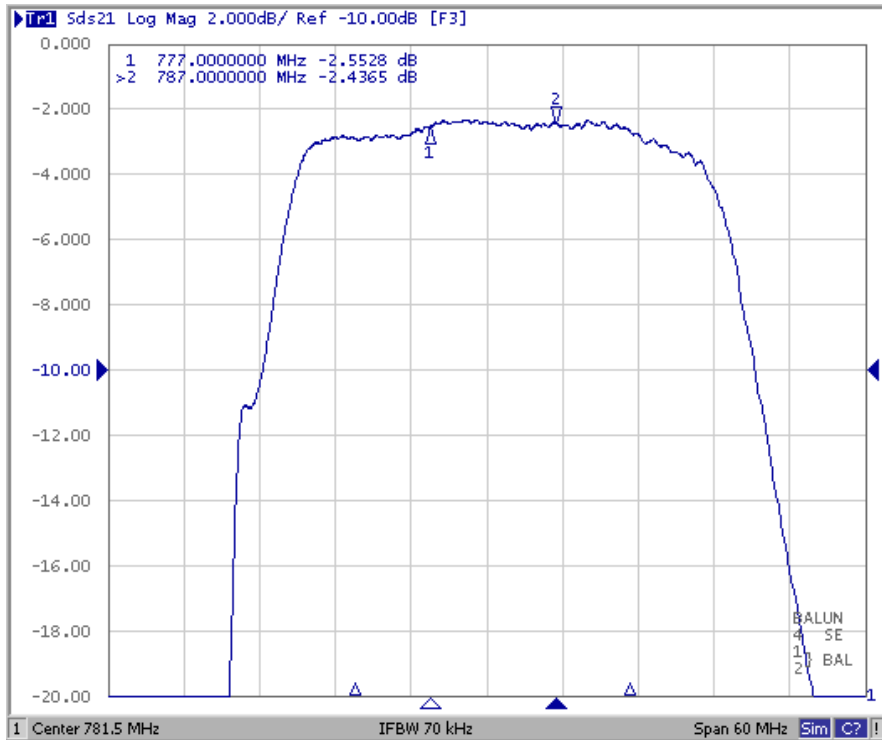
#### Measurement Circuit:



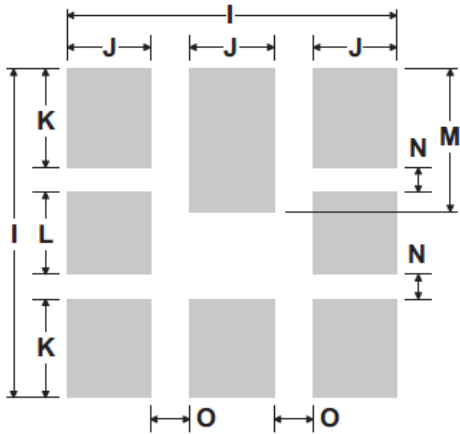
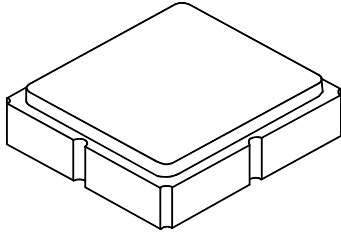
**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**  
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

# Filter Response Plots



## 8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



**PCB Footprint Top View**

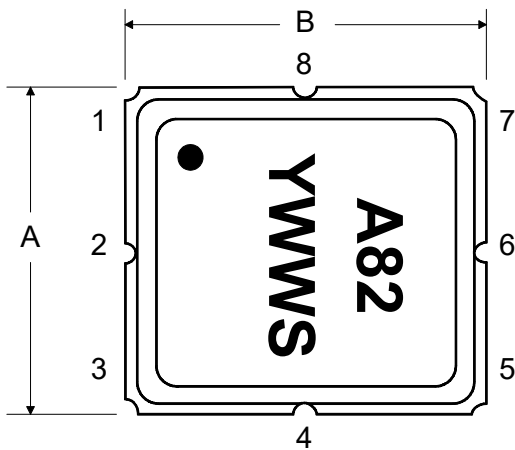
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

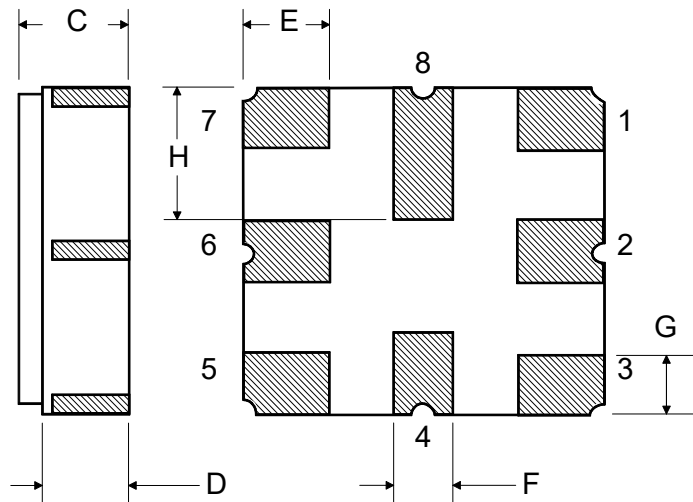
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu$ m Gold over 1.27 to 8.89 $\mu$ m Nickel
Lid Plating	2.0 to 3.0 $\mu$ m Nickel
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic

**TOP VIEW**



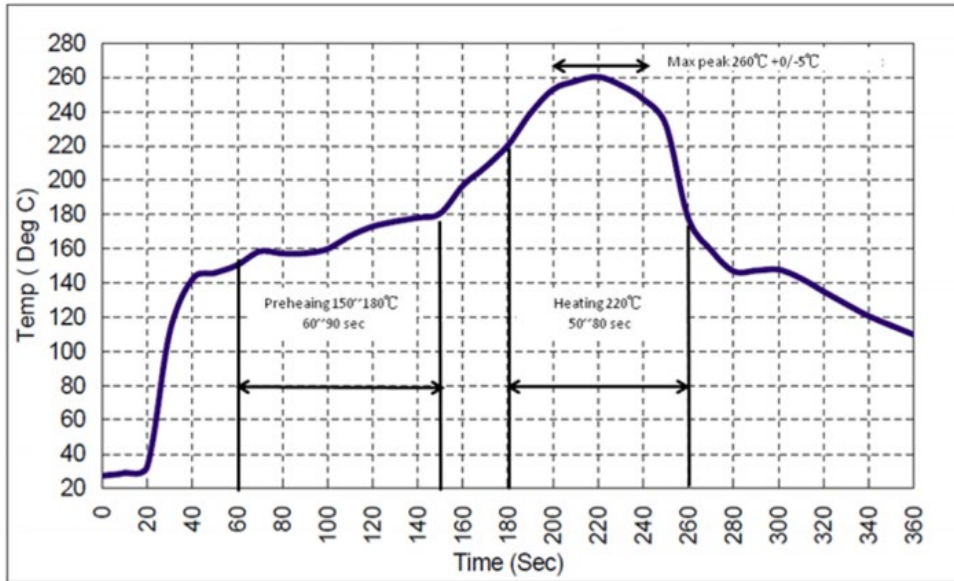
**BOTTOM VIEW**







## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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-  [RF Monolithics, Inc Information](#)

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